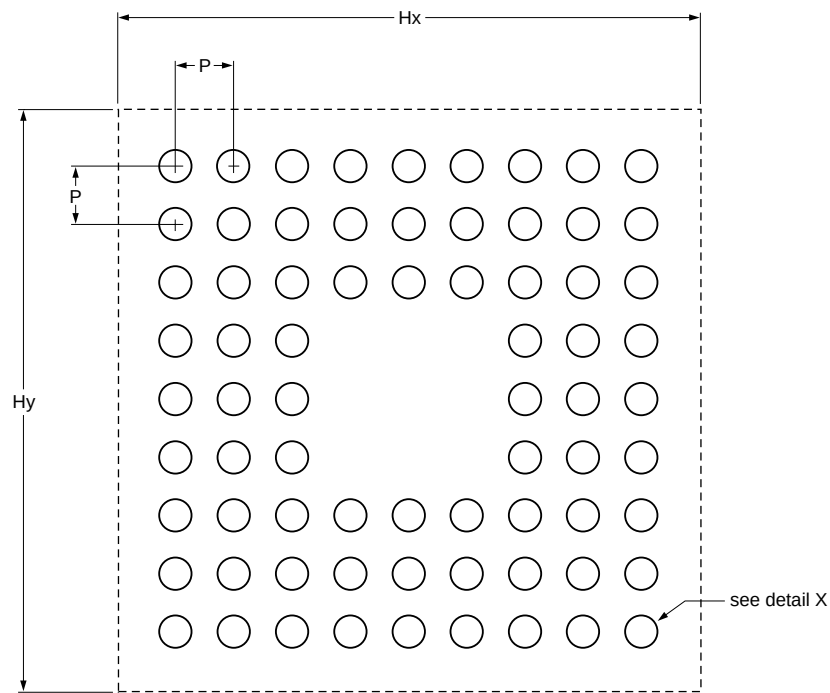


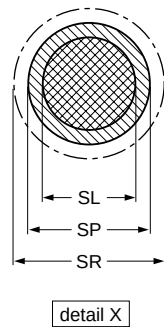
Footprint information for reflow soldering of VFBGA144 package

SOT1078-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

- solder land
- solder paste deposit
- solder land plus solder paste
- occupied area
- solder resist



DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.40	0.250	0.275	0.350	5.900	5.900